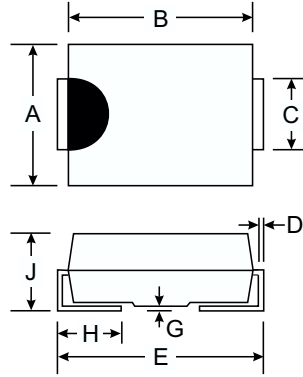


### Features

- Glass Passivated Die Construction
- Super-Fast Recovery Time For High Efficiency
- Low Forward Voltage Drop and High Current Capability
- Surge Overload Rating to 50A Peak
- Ideally Suited for Automated Assembly
- Plastic Material: UL Flammability Classification Rating 94V-0



Dim	SMA		SMB	
	Min	Max	Min	Max
A	2.29	2.92	3.30	3.94
B	4.00	4.60	4.06	4.57
C	1.27	1.63	1.96	2.21
D	0.15	0.31	0.15	0.31
E	4.80	5.59	5.00	5.59
G	0.10	0.20	0.10	0.20
H	0.76	1.52	0.76	1.52
J	2.01	2.62	2.00	2.62

**All Dimensions in mm**

AA, BA, CA, DA Suffix Designates SMA Package  
A, B, C, D, Suffix Designates SMB Package

### Mechanical Data

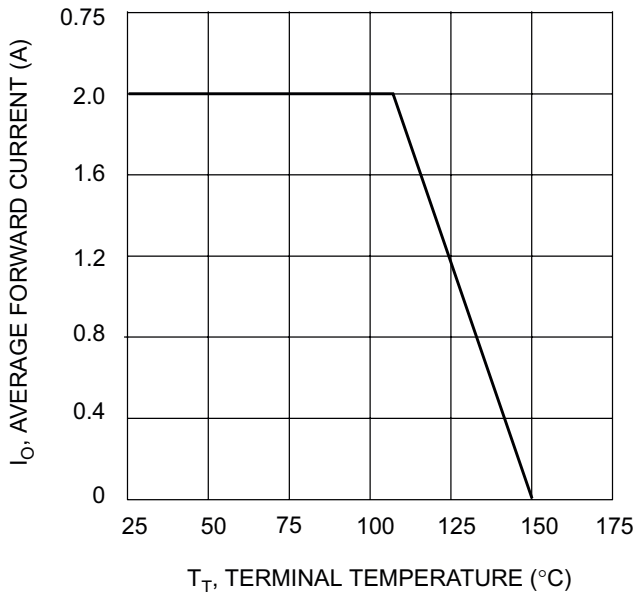
- Case: Molded Plastic
- Terminals: Solder Plated Terminal - Solderable per MIL-STD-202, Method 208
- Polarity: Cathode Band or Cathode Notch
- SMA Weight: 0.064 grams (approx.)
- SMB Weight: 0.093 grams (approx.)
- Mounting Position: Any
- Marking: Type Number

### Maximum Ratings and Electrical Characteristics @ T<sub>A</sub> = 25°C unless otherwise specified

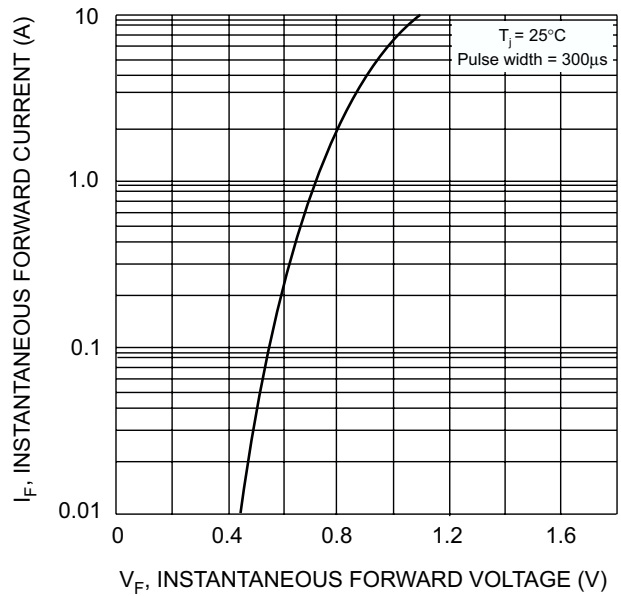
Single phase, half wave, 60Hz, resistive or inductive load.  
For capacitive load, derate current by 20%.

Characteristic	Symbol	ES2A/A	ES2B/A	ES2C/A	ES2D/A	Unit
Peak Repetitive Reverse Voltage	V <sub>RRM</sub>	50	100	150	200	V
Working Peak Reverse Voltage	V <sub>RWM</sub>					
DC Blocking Voltage	V <sub>R</sub>					
RMS Reverse Voltage	V <sub>R(RMS)</sub>	35	70	105	140	V
Average Rectified Output Current @ T <sub>T</sub> = 110°C	I <sub>O</sub>	2.0				A
Non-Repetitive Peak Forward Surge Current 8.3ms Single half sine-wave Superimposed on Rated Load (JEDEC Method)	I <sub>FSM</sub>	50				A
Forward Voltage @ I <sub>F</sub> = 2.0A	V <sub>FM</sub>	0.92				V
Peak Reverse Current @ T <sub>A</sub> = 25°C at Rated DC Blocking Voltage @ T <sub>A</sub> = 125°C	I <sub>RM</sub>	5.0 350				μA
Reverse Recovery Time (Note 3)	t <sub>rr</sub>	25				ns
Typical Junction Capacitance (Note 2)	C <sub>j</sub>	25				pF
Typical Thermal Resistance, Junction to Terminal (Note 1)	R <sub>θJT</sub>	20				°C/W
Operating and Storage Temperature Range	T <sub>j</sub> , T <sub>STG</sub>	-55 to +150				°C

- Notes:
1. Unit mounted on PC board with 5.0 mm<sup>2</sup> (0.013 mm thick) copper pads as heat sink.
  2. Measured at 1.0MHz and applied reverse voltage of 4.0V DC.
  3. Measured with I<sub>F</sub> = 0.5A, I<sub>R</sub> = 1.0A, I<sub>rr</sub> = 0.25A. See Figure 5.



$T_T$ , TERMINAL TEMPERATURE (°C)  
Fig. 1 Forward Current Derating Curve



$V_F$ , INSTANTANEOUS FORWARD VOLTAGE (V)  
Fig. 2 Typical Forward Characteristics

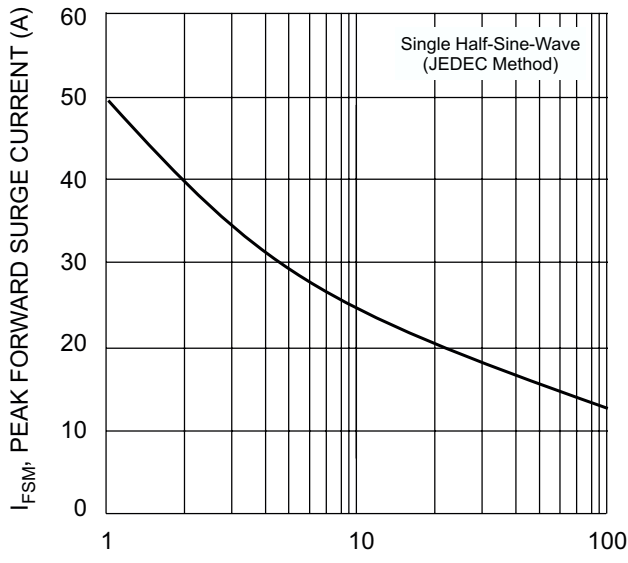


Fig. 3 Surge Current Derating Curve

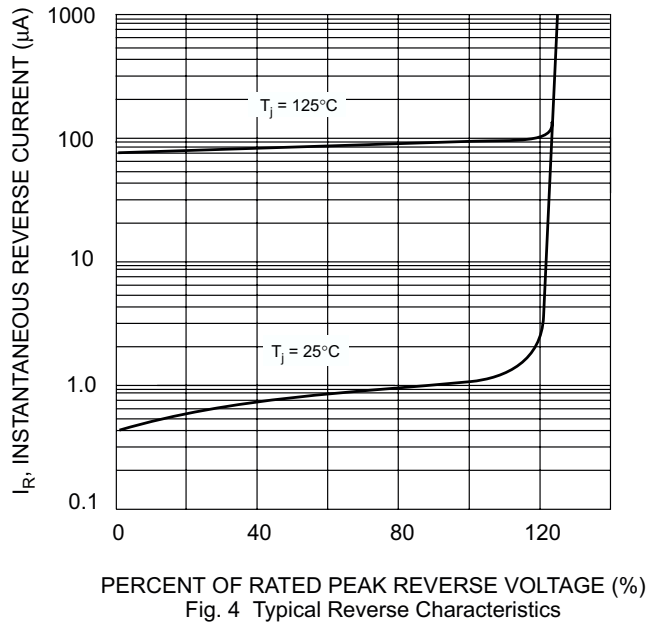
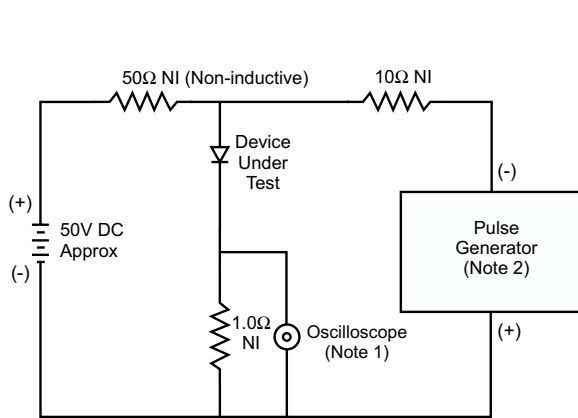
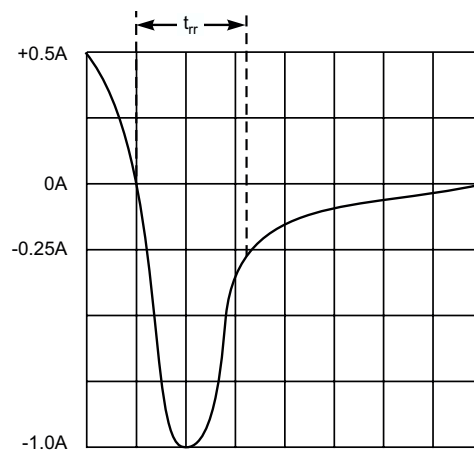


Fig. 4 Typical Reverse Characteristics



Notes:  
1. Rise Time = 7.0ns max. Input Impedance = 1.0MΩ, 22pF.  
2. Rise Time = 10ns max. Input Impedance = 50Ω.



Set time base for 50/100 ns/cm

Fig. 5 Reverse Recovery Time Characteristic and Test Circuit